



#6/B
5/22/02
PATENT Mollish

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

HUANG et al.

Serial No.: 09/736,225

Filed: December 15, 2000

For: SEMICONDUCTOR PACKAGE WITHOUT SUBSTRATE
AND METHOD OF MANUFACTURING SAME

Group Art Unit: 2811

Examiner: N. Parekh

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MAY 15 2002
TECHNOLOGY CENTER 2800

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

This is in response to the Official Action of February 15, 2002, in connection with the above-identified application.

Please amend the above-identified application as follows.

IN THE CLAIMS:

Please add the following new claims to the application.

17(New). A single semiconductor package consisting of a solder mask layer formed at selected locations and intermediate and contiguous thereto a lead layer and a die pad layer, said die pad layer has a chip adhering to the die pad layer; a plurality of conductive elements are electrically connecting the chip and the lead layer; and a molded resin covering the chip, conductive elements, solder masks, lead layer and die pad layer.